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Understanding <u>Embedded - DSP (Digital Signal Processors)</u>

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of <u>Embedded - DSP (Digital Signal Processors)</u>

Details	
Product Status	Active
уре	Floating Point
nterface	CAN, EBI/EMI, Ethernet, DAI, I ² C, MMC/SD/SDIO, SPI, SPORT, UART/USART, USB OTG
lock Rate	300MHz
Ion-Volatile Memory	ROM (512kB)
n-Chip RAM	384kB
oltage - I/O	3.30V
oltage - Core	1.10V
perating Temperature	-40°C ~ 95°C (TA)
ounting Type	Surface Mount
ackage / Case	349-LFBGA, CSPBGA
upplier Device Package	349-CSPBGA (19x19)
urchase URL	https://www.e-xfl.com/product-detail/analog-devices/adsp-sc583cbcz-3a

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

ARM CORTEX-A5 PROCESSOR

The ARM Cortex-A5 processor (see Figure 2) is a high performance processor with the following features:

- Instruction cache unit (32 Kb) and data L1 cache unit (32 Kb)
- In order pipeline with dynamic branch prediction
- ARM, Thumb, and ThumbEE instruction set support
- ARM TrustZone® security extensions

- Harvard L1 memory system with a memory management unit (MMU)
- ARM v7 debug architecture
- Trace support through an embedded trace macrocell (ETM) interface
- Extension—vector floating-point unit (IEEE 754) with trapless execution
- Extension—media processing engine (MPE) with NEON[™] technology
- Extension—Jazelle hardware acceleration

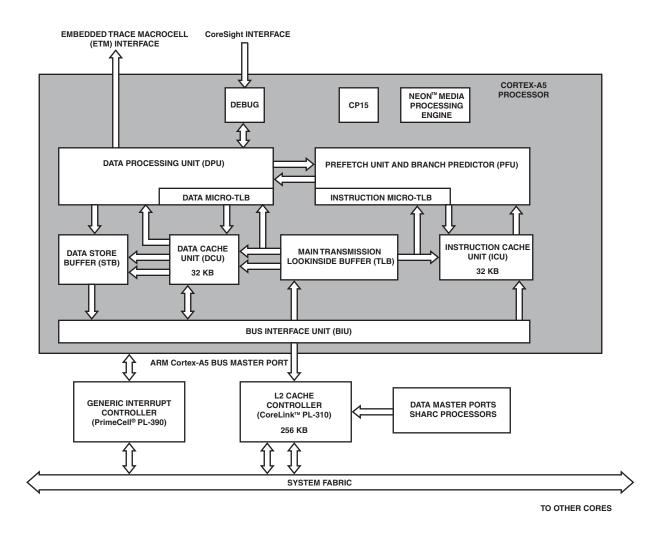


Figure 2. ARM Cortex-A5 Processor Block Diagram

Table 7. Memory Map of Mapped I/Os

	Byte Address Space		SHARC+ Core I	nstruction Fetch
	ARM Cortex-A5 – Data Access and Instruction Fetch SHARC+ – Data Access	Normal Word Address Space for Data Access SHARC+	VISA Space	ISA Space
SMC Bank 0 (64 MB)	0x40000000-0x43FFFFFF	0x01000000-0x01FFFFFF	0x00F00000-0x00F3FFFF	0x00700000-0x0073FFFF
SMC Bank 1 (64 MB)	0x44000000-0x47FFFFF	Not applicable	Not applicable	Not applicable
SMC Bank 2 (64 MB)	0x48000000-0x4BFFFFFF	Not applicable	Not applicable	Not applicable
SMC Bank 3 (64 MB)	0x4C000000-0x4FFFFFF	Not applicable	Not applicable	Not applicable
PCIe Data (256 MB)	0x50000000-0x5FFFFFF	0x02000000-0x03FFFFFF	0x00F40000-0x00F7FFF	0x00740000-0x0077FFFF
SPI2 Memory (512 MB)	0x60000000-0x7FFFFFF	0x04000000-0x07FFFFF	0x00F80000-0x00FFFFF	0x00780000-0x007FFFF

Table 8. DMC Memory Map

	Byte Address Space	ess Space		SHARC+ Core Instruction Fetch	
	ARM Cortex-A5 – Data Access and Instruction Fetch SHARC+ – Data Access	Normal Word Address Space for Data Access SHARC+	VISA Space	ISA Space	
DMC0 (1 GB)	0x80000000-0xBFFFFFF	0x10000000-0x17FFFFF	0x00800000-0x00AFFFFF	0x00400000-0x004FFFFF	
DMC1 (1 GB)	0xC0000000-0xFFFFFFF	0x18000000-0x1FFFFFF	0x00C00000-0x00EFFFFF	0x00600000-0x006FFFFF	

System Crossbars (SCBs)

The system crossbars (SCBs) are the fundamental building blocks of a switch-fabric style for on-chip system bus interconnection. The SCBs connect system bus masters to system bus slaves, providing concurrent data transfer between multiple bus masters and multiple bus slaves. A hierarchical model—built from multiple SCBs—provides a power and area efficient system interconnection.

The SCBs provide the following features:

- Highly efficient, pipelined bus transfer protocol for sustained throughput
- Full-duplex bus operation for flexibility and reduced latency
- Concurrent bus transfer support to allow multiple bus masters to access bus slaves simultaneously
- Protection model (privileged/secure) support for selective bus interconnect protection

Direct Memory Access (DMA)

The processors use direct memory access (DMA) to transfer data within memory spaces or between a memory space and a peripheral. The processors can specify data transfer operations and return to normal processing while the fully integrated DMA controller carries out the data transfers independent of processor activity.

DMA transfers can occur between memory and a peripheral or between one memory and another memory. Each memory to memory DMA stream uses two channels: one channel is the source channel and the second is the destination channel.

All DMA channels can transport data to and from all on-chip and off-chip memories. Programs can use two types of DMA transfers: descriptor-based or register-based.

Register-based DMA allows the processors to program DMA control registers directly to initiate a DMA transfer. On completion, the DMA control registers automatically update with original setup values for continuous transfer. Descriptor-based DMA transfers require a set of parameters stored within memory to initiate a DMA sequence. Descriptor-based DMA transfers allow multiple DMA sequences to be chained together. Program a DMA channel to set up and start another DMA transfer automatically after the current sequence completes.

The DMA engine supports the following DMA operations:

- A single linear buffer that stops on completion
- A linear buffer with negative, positive, or zero stride length
- A circular autorefreshing buffer that interrupts when each buffer becomes full
- A similar circular buffer that interrupts on fractional buffers, such as at the halfway point
- The 1D DMA uses a set of identical ping pong buffers defined by a linked ring of two-word descriptor sets, each containing a link pointer and an address
- The 1D DMA uses a linked list of four-word descriptor sets containing a link pointer, an address, a length, and a configuration
- The 2D DMA uses an array of one-word descriptor sets, specifying only the base DMA address
- The 2D DMA uses a linked list of multiword descriptor sets, specifying all configurable parameters

Memory Direct Memory Access (MDMA)

The processor supports various MDMA operations, including,

- Standard bandwidth MDMA channels with CRC protection (32-bit bus width, runs on SCLK0)
- Enhanced bandwidth MDMA channel (32-bit bus width, runs on SYSCLK)
- Maximum bandwidth MDMA channels (64-bit bus width, run on SYCLK, one channel can be assigned to the FFT accelerator)

Extended Memory DMA

Extended memory DMA supports various operating modes such as delay line (which allows processor reads and writes to external delay line buffers and to the external memory) with limited core interaction and scatter/gather DMA (writes to and from noncontiguous memory blocks).

Cyclic Redundant C ode (CRC) Protection

The cyclic redundant codes (CRC) protection modules allow system software to calculate the signature of code, data, or both in memory, the content of memory-mapped registers, or periodic communication message objects. Dedicated hardware circuitry compares the signature with precalculated values and triggers appropriate fault events.

For example, every 100 ms the system software initiates the signature calculation of the entire memory contents and compares these contents with expected, precalculated values. If a mismatch occurs, a fault condition is generated through the processor core or the trigger routing unit.

The CRC is a hardware module based on a CRC32 engine that computes the CRC value of the 32-bit data-words presented to it. The source channel of the memory to memory DMA (in memory scan mode) provides data. The data can be optionally forwarded to the destination channel (memory transfer mode). The main features of the CRC peripheral are as follows:

- · Memory scan mode
- Memory transfer mode
- · Data verify mode
- Data fill mode
- User-programmable CRC32 polynomial
- Bit/byte mirroring option (endianness)
- Fault/error interrupt mechanisms
- 1D and 2D fill block to initialize an array with constants
- 32-bit CRC signature of a block of a memory or an MMR block

Event Handling

The processors provide event handling that supports both nesting and prioritization. Nesting allows multiple event service routines to be active simultaneously. Prioritization ensures that servicing a higher priority event takes precedence over servicing a lower priority event.

The processors provide support for five different types of events:

- An emulation event causes the processors to enter emulation mode, allowing command and control of the processors through the JTAG interface.
- A reset event resets the processors.
- An exceptions event occur synchronously to program flow (in other words, the exception is taken before the instruction is allowed to complete). Conditions triggered on the one side by the SHARC+ core, such as data alignment (SIMD/long word) or compute violations (fixed or floating point), and illegal instructions cause core exceptions. Conditions triggered on the other side by the SEC, such as error correcting codes (ECC)/parity/watchdog/system clock, cause system exceptions.
- An interrupts event occurs asynchronously to program flow. They are caused by input signals, timers, and other peripherals, as well as by an explicit software instruction.

System Event Controller (SEC)

Both SHARC+ cores feature a system event controller. The SEC features include the following:

- Comprehensive system event source management including interrupt enable, fault enable, priority, core mapping, and source grouping
- A distributed programming model where each system event source control and all status fields are independent of each other
- Determinism where all system events have the same propagation delay and provide unique identification of a specific system event source
- A slave control port that provides access to all SEC registers for configuration, status, and interrupt/fault services
- Global locking that supports a register level protection model to prevent writes to locked registers
- Fault management including fault action configuration, time out, external indication, and system reset

Trigger Routing Unit (TRU)

The trigger routing unit (TRU) provides system-level sequence control without core intervention. The TRU maps trigger masters (generators of triggers) to trigger slaves (receivers of triggers). Slave endpoints can be configured to respond to triggers in various ways. Common applications enabled by the TRU include,

- Automatically triggering the start of a DMA sequence after a sequence from another DMA channel completes
- Software triggering
- Synchronization of concurrent activities

The reset target is defined as the following:

- System reset—all functional units except the RCU are set to default states.
- Hardware reset—all functional units are set to default states without exception. History is lost.
- Core only reset— affects the core only. When in reset state, the core is not accessed by any bus master.

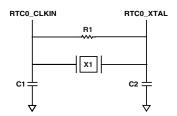
The reset source is defined as the following:

- System reset—can be triggered by software (writing to the RCU_CTL register) or by another functional unit such as the dynamic power management (DPM) unit or any of the SEC, TRU, or emulator inputs.
- Hardware reset—the SYS_HWRST input signal asserts active (pulled down).
- Core only reset—affects only the core. The core is not accessed by any bus master when in reset state.
- Trigger request (peripheral).

Real-Time Clock (RTC)

The real-time clock (RTC) provides a robust set of digital watch features, including current time, stopwatch, and alarm. The RTC is clocked by a 32.768 kHz crystal external to the processor. Connect the RTC0_CLKIN and RTC0_XTAL pins with external components as shown in Figure 6.

The RTC peripheral has dedicated power supply pins so it can remain powered up and clocked even when the remainder of the processor is in a low power state. The RTC provides several programmable interrupt options, including interrupt per second, minute, hour, or day clock ticks; interrupt on programmable stopwatch countdown; or interrupt at a programmed alarm time.



NOTE: C1 AND C2 ARE SPECIFIC TO CRYSTAL SPECIFIED FOR X1. CONTACT CRYSTAL MANUFACTURER FOR DETAILS.

Figure 6. External Components for RTC

The 32.768 kHz input clock frequency is divided down to a 1 Hz signal by a prescaler. The counter function of the timer consists of four counters: a 60 second counter, a 60 minute counter, a 24 hour counter, and a 32,768 day counter. When the alarm interrupt is enabled, the alarm function generates an interrupt when the output of the timer matches the programmed value in the alarm control register (RTC_ALARM). There are two alarms: a time of day and a day and time of that day.

The stopwatch function counts down from a programmed value, with 1 sec resolution. When the stopwatch interrupt is enabled and the counter underflows, an interrupt is generated.

Clock Generation Unit (CGU)

The ADSP-SC58x/ADSP-2158x processors support two independent PLLs. Each PLL is part of a clock generation unit (CGU); see Figure 8. Each CGU can be either driven externally by the same clock source or each can be driven by separate sources. This provides flexibility in determining the internal clocking frequencies for each clock domain.

Frequencies generated by each CGU are derived from a common multiplier with different divider values available for each output.

The CGU generates all on-chip clocks and synchronization signals. Multiplication factors are programmed to define the PLLCLK frequency.

Programmable values divide the PLLCLK frequency to generate the core clock (CCLK), the system clocks, the DDR1/DDR2/DDR3 clock (DCLK), and the output clock (OCLK). For more information on clocking, see the ADSP-SC58x/ADSP-2158x SHARC+ Processor Hardware Reference.

Writing to the CGU control registers does not affect the behavior of the PLL immediately. Registers are first programmed with a new value and the PLL logic executes the changes so it transitions smoothly from the current conditions to the new conditions.

System Crystal Oscillator and USB Crystal Oscillator

The processor can be clocked by an external crystal (see Figure 7), a sine wave input, or a buffered, shaped clock derived from an external clock oscillator. If using an external clock, it should be a TTL-compatible signal and must not be halted, changed, or operated below the specified frequency during normal operation. This signal is connected to the SYS_CLKINx pin and the USB_CLKIN pin of the processor. When using an external clock, the SYS_XTALx pin and the USB_XTAL pin must be left unconnected. Alternatively, because the processor includes an on-chip oscillator circuit, an external crystal can be used.

For fundamental frequency operation, use the circuit shown in Figure 7. A parallel resonant, fundamental frequency, microprocessor grade crystal is connected across the SYS_CLKINx pin and the SYS_XTALx pin. The on-chip resistance between the SYS_CLKINx pin and the SYS_XTALx pin is in the 500 k Ω range. Further parallel resistors are typically not recommended.

The two capacitors and the series resistor, shown in Figure 7, fine tune phase and amplitude of the sine frequency. The capacitor and resistor values shown in Figure 7 are typical values only. The capacitor values are dependent upon the load capacitance recommendations of the crystal manufacturer and the physical layout of the printed circuit board (PCB). The resistor value depends on the drive level specified by the crystal manufacturer. The user must verify the customized values based on careful investigations on multiple devices over the required temperature range.

Table 11. ADSP-SC58x/ADSP-2158x Detailed Signal Descriptions (Continued)

Signal Name	Direction	Description
SMC_ABE[n]	Output	Byte Enable n. Indicates whether the lower or upper byte of a memory is being accessed. When an
		asynchronous write is made to the upper byte of a 16-bit memory, SMC_ABE1 = 0 and
		SMC_ABEO = 1. When an asynchronous write is made to the lower byte of a 16-bit memory,
CLIC ALICE 1		$\overline{SMC_ABE1} = 1 \text{ and } \overline{SMC_ABE0} = 0.$
SMC_AMS[n]	Output	Memory Select n. Typically connects to the chip select of a memory device.
SMC_AOE	Output	Output Enable. Asserts at the beginning of the setup period of a read access.
SMC_ARDY	Input	Asynchronous Ready. Flow control signal used by memory devices to indicate to the SMC when
SMC_ARE	Output	further transactions may proceed.
	Output	Read Enable. Asserts at the beginning of a read access.
SMC_AWE	Output	Write Enable. Asserts for the duration of a write access period.
SMC_A[nn]	Output	Address n. Address bus.
SMC_D[nn]	InOut	Data n. Bidirectional data bus.
SPI_CLK	InOut	Clock. Input in slave mode, output in master mode.
SPI_D2	InOut	Data 2. Transfers serial data in quad mode. Open-drain when ODM mode is enabled.
SPI_D3	InOut	Data 3. Transfers serial data in quad mode. Open-drain when ODM mode is enabled.
SPI_MISO	InOut	Master In, Slave Out. Transfers serial data. Operates in the same direction as SPI_MOSI in dual and quad modes. Open-drain when ODM mode is enabled.
SPI_MOSI	InOut	Master Out, Slave In. Transfers serial data. Operates in the same direction as SPI_MISO in dual and quad modes. Open-drain when ODM mode is enabled.
SPI_RDY	InOut	Ready. Optional flow signal. Output in slave mode, input in master mode.
SPI_SEL[n]	Output	Slave Select Output n. Used in master mode to enable the desired slave.
SPI_SS	Input	Slave Select Input.
		Slave mode—acts as the slave select input.
		Master mode—optionally serves as an error detection input for the SPI when there are multiple masters.
SPT_ACLK	InOut	Channel A Clock. Data and frame sync are driven/sampled with respect to this clock. This signal car be either internally or externally generated.
SPT_AD0	InOut	Channel A Data 0. Primary bidirectional data I/O. This signal can be configured as an output to transmit serial data or as an input to receive serial data.
SPT_AD1	InOut	Channel A Data 1. Secondary bidirectional data I/O. This signal can be configured as an output to transmit serial data or as an input to receive serial data.
SPT_AFS	InOut	Channel A Frame Sync. The frame sync pulse initiates shifting of the serial data. This signal is either generated internally or externally.
SPT_ATDV	Output	Channel A Transmit Data Valid. This signal is optional and only active when SPORT is configured in multichannel transmit mode. It is asserted during enabled slots.
SPT_BCLK	InOut	Channel B Clock. Data and frame sync are driven/sampled with respect to this clock. This signal car be either internally or externally generated.
SPT_BD0	InOut	Channel B Data 0. Primary bidirectional data I/O. This signal can be configured as an output to transmit serial data or as an input to receive serial data.
SPT_BD1	InOut	Channel B Data 1. Secondary bidirectional data I/O. This signal can be configured as an output to transmit serial data or as an input to receive serial data.
SPT_BFS	InOut	Channel B Frame Sync. The frame sync pulse initiates shifting of serial data. This signal is either generated internally or externally.
SPT_BTDV	Output	Channel B Transmit Data Valid. This signal is optional and only active when SPORT is configured in multichannel transmit mode. It is asserted during enabled slots.
SYS_BMODE[n]	Input	Boot Mode Control n. Selects the boot mode of the processor.
SYS_CLKIN0	Input	Clock/Crystal Input.
SYS_CLKIN1	Input	Clock/Crystal Input.
SYS_CLKOUT	Output	Processor Clock Output. Outputs internal clocks. Clocks may be divided down. See the CGU chapte
5.5_CENOO1	Juiput	of the ADSP-SC58x/ADSP-2158x SHARC+ Processor Hardware Reference for more details.

349-BALL CSP_BGA SIGNAL DESCRIPTIONS

The processor pin definitions are shown in Table 12 for the 349-ball CSP_BGA package. The columns in this table provide the following information:

- The signal name column includes the signal name for every pin and the GPIO multiplexed pin function, where applicable.
- The description column provides a descriptive name for each signal.
- The port column shows whether or not a signal is multiplexed with other signals on a general-purpose I/O port pin.
- The pin name column identifies the name of the package pin (at power on reset) on which the signal is located (if a single function pin) or is multiplexed (if a general-purpose I/O pin).
- The DAI pins and their associated signal routing units (SRUs) connect inputs and outputs of the DAI peripherals (SPORT, ASRC, S/PDIF, and PCG). See the Digital Audio Interface (DAI) chapter of the ADSP-SC58x/ADSP-2158x SHARC+ Processor Hardware Reference for complete information on the use of the DAI and SRUs.

Table 12. ADSP-SC58x/ADSP-2158x 349-Ball CSP_BGA Signal Descriptions

Signal Name	Description	Port	Pin Name
ACM0_A0	ACM0 ADC Control Signals	С	PC_13
ACM0_A1	ACM0 ADC Control Signals	C	PC_14
ACM0_A2	ACM0 ADC Control Signals	C	PC_15
ACM0_A3	ACM0 ADC Control Signals	D	PD_00
ACM0_A4	ACM0 ADC Control Signals	D	PD_01
ACM0_T0	ACM0 External Trigger n	C	PC_12
C1_FLG0	SHARC Core 1 Flag Pin	E	PE_01
C1_FLG1	SHARC Core 1 Flag Pin	E	PE_03
C1_FLG2	SHARC Core 1 Flag Pin	E	PE_05
C1_FLG3	SHARC Core 1 Flag Pin	E	PE_07
C2_FLG0	SHARC Core 2 Flag Pin	E	PE_02
C2_FLG1	SHARC Core 2 Flag Pin	E	PE_04
C2_FLG2	SHARC Core 2 Flag Pin	E	PE_06
C2_FLG3	SHARC Core 2 Flag Pin	E	PE_08
CAN0_RX	CAN0 Receive	C	PC_07
CAN0_TX	CAN0 Transmit	C	PC_08
CAN1_RX	CAN1 Receive	В	PB_10
CAN1_TX	CAN1 Transmit	В	PB_09
CNT0_DG	CNT0 Count Down and Gate	В	PB_14
CNT0_UD	CNT0 Count Up and Direction	В	PB_12
CNT0_ZM	CNT0 Count Zero Marker	В	PB_11
DAI0_PIN01	DAI0 Pin 1	Not Muxed	DAI0_PIN01
DAI0_PIN02	DAI0 Pin 2	Not Muxed	DAI0_PIN02
DAI0_PIN03	DAI0 Pin 3	Not Muxed	DAI0_PIN03
DAI0_PIN04	DAI0 Pin 4	Not Muxed	DAI0_PIN04
DAI0_PIN05	DAI0 Pin 5	Not Muxed	DAI0_PIN05
DAI0_PIN06	DAI0 Pin 6	Not Muxed	DAI0_PIN06
DAI0_PIN07	DAI0 Pin 7	Not Muxed	DAI0_PIN07
DAI0_PIN08	DAI0 Pin 8	Not Muxed	DAI0_PIN08
DAI0_PIN09	DAI0 Pin 9	Not Muxed	DAI0_PIN09
DAI0_PIN10	DAI0 Pin 10	Not Muxed	DAI0_PIN10
DAI0_PIN11	DAI0 Pin 11	Not Muxed	DAI0_PIN11
DAI0_PIN12	DAI0 Pin 12	Not Muxed	DAI0_PIN12
DAI0_PIN19	DAI0 Pin 19	Not Muxed	DAI0_PIN19
DAI0_PIN20	DAI0 Pin 20	Not Muxed	DAI0_PIN20

Table 12. ADSP-SC58x/ADSP-2158x 349-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
HADC0_VIN5	HADC0 Analog Input at channel 5	Not Muxed	HADC0_VIN5
HADC0_VIN6	HADC0 Analog Input at channel 6	Not Muxed	HADC0_VIN6
HADC0_VIN7	HADCO Analog Input at channel 7	Not Muxed	HADC0_VIN7
HADC0_VREFN	HADC0 Ground Reference for ADC	Not Muxed	HADC0_VREFN
HADC0_VREFP	HADC0 External Reference for ADC	Not Muxed	HADC0_VREFP
JTG_TCK	TAPC JTAG Clock	Not Muxed	JTG_TCK
JTG_TDI	TAPC JTAG Serial Data In	Not Muxed	JTG_TDI
JTG_TDO	TAPC JTAG Serial Data Out	Not Muxed	JTG_TDO
JTG_TMS	TAPC JTAG Mode Select	Not Muxed	JTG_TMS
JTG_TRST	TAPC JTAG Reset	Not Muxed	JTG_TRST
LP0_ACK	LP0 Acknowledge	D	PD_11
LP0_CLK	LP0 Clock	D	PD_10
LP0_D0	LP0 Data 0	D	PD_02
LP0_D1	LP0 Data 1	D	PD_03
LP0_D2	LP0 Data 2	D	PD_04
LP0_D3	LP0 Data 3	D	PD_05
LP0_D4	LP0 Data 4	D	PD_06
LP0_D5	LP0 Data 5	D	PD_07
LP0_D6	LP0 Data 6	D	PD_08
LP0_D7	LP0 Data 7	D	PD_09
LP1_ACK	LP1 Acknowledge	В	PB_15
LP1_CLK	LP1 Clock	С	PC_00
LP1_D0	LP1 Data 0	В	PB_07
LP1_D1	LP1 Data 1	В	PB_08
LP1_D2	LP1 Data 2	В	PB_09
LP1_D3	LP1 Data 3	В	PB_10
LP1_D4	LP1 Data 4	В	PB_11
LP1_D5	LP1 Data 5	В	PB_12
LP1_D6	LP1 Data 6	В	PB_13
LP1_D7	LP1 Data 7	В	PB_14
MLB0_CLKN	MLB0 Negative Differential Clock (–)	Not Muxed	MLB0_CLKN
MLB0_CLKP	MLB0 Positive Differential Clock (+)	Not Muxed	MLB0_CLKP
MLB0_DATN	MLB0 Negative Differential Data (–)	Not Muxed	MLB0_DATN
MLB0_DATP	MLB0 Positive Differential Data (+)	Not Muxed	MLB0_DATP
MLB0_SIGN	MLB0 Negative Differential Signal (–)	Not Muxed	MLB0_SIGN
MLB0_SIGP	MLB0 Positive Differential Signal (+)	Not Muxed	MLB0_SIGP
MLB0_CLK	MLB0 Single-Ended Clock	В	PB_04
MLB0_DAT	MLB0 Single-Ended Data	В	PB_06
MLB0_SIG	MLB0 Single-Ended Signal	В	PB_05
MLB0_CLKOUT	MLB0 Single-Ended Clock Out	D	PD_14
PA_00-15	PORTA Position 00 through Position 15	Α	PA_00-15
PB_00-15	PORTB Position 00 through Position 15	В	PB_00-15
PC_00-15	PORTC Position 00 through Position 15	С	PC_00-15
PD_00-15	PORTD Position 00 through Position 15	D	PD_00-15
PE_00-15	PORTE Position 00 through Position 15	E	PE_00-15
PPIO_CLK	EPPI0 Clock	E	PE_03
PPI0_D00	EPPIO Data 0	E	PE_12
PPI0_D01	EPPI0 Data 1	E	PE_11

Table 12. ADSP-SC58x/ADSP-2158x 349-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
SYS_BMODE0	Boot Mode Control n	Not Muxed	SYS_BMODE0
SYS_BMODE1	Boot Mode Control n	Not Muxed	SYS_BMODE1
SYS_BMODE2	Boot Mode Control n	Not Muxed	SYS_BMODE2
SYS_CLKIN0	Clock/Crystal Input	Not Muxed	SYS_CLKIN0
SYS_CLKIN1	Clock/Crystal Input	Not Muxed	SYS_CLKIN1
SYS_CLKOUT	Processor Clock Output	Not Muxed	SYS_CLKOUT
SYS_FAULT	Active High Fault Output	Not Muxed	SYS_FAULT
SYS_FAULT	Active Low Fault Output	Not Muxed	SYS_FAULT
SYS_HWRST	Processor Hardware Reset Control	Not Muxed	SYS_HWRST
SYS_RESOUT	Reset Output	Not Muxed	SYS_RESOUT
SYS_XTAL0	Crystal Output	Not Muxed	SYS_XTAL0
SYS_XTAL1	Crystal Output	Not Muxed	SYS_XTAL1
TM0_ACI0	TIMERO Alternate Capture Input 0	c	PC_14
TM0_ACI1	TIMERO Alternate Capture Input 1	В	PB_03
TM0_ACI2	TIMERO Alternate Capture Input 2	D	PD_13
TM0_ACI3	TIMERO Alternate Capture Input 3	c	PC_07
TM0_ACI4	TIMERO Alternate Capture Input 4	В	PB_10
TM0_ACLK1	TIMERO Alternate Clock 1	D	PD_08
TM0_ACLK2	TIMERO Alternate Clock 2	D	PD_09
TM0_ACLK3	TIMERO Alternate Clock 3	В	PB_00
TM0_ACLK4	TIMERO Alternate Clock 4	В	PB_01
TM0_CLK	TIMER0 Clock	c	PC_11
TM0_TMR0	TIMER0 Timer 0	E	PE_09
TM0_TMR1	TIMER0 Timer 1	В	PB_15
TM0_TMR2	TIMER0 Timer 2	В	PB_10
TM0_TMR3	TIMER0 Timer 3	В	PB_07
TM0_TMR4	TIMER0 Timer 4	В	PB_08
TM0_TMR5	TIMER0 Timer 5	В	PB_14
TRACEO_CLK	TRACE0 Trace Clock	D	PD_10
TRACE0_D00	TRACE0 Trace Data 0	D	PD_02
TRACE0_D01	TRACE0 Trace Data 1	D	PD_03
TRACE0_D02	TRACE0 Trace Data 2	D	PD_04
TRACEO_D03	TRACE0 Trace Data 3	D	PD_05
TRACE0_D04	TRACEO Trace Data 4	D	PD_06
TRACEO_D05	TRACEO Trace Data 5	D	PD_07
TRACE0_D06	TRACE0 Trace Data 6	D	PD_08
TRACE0_D07	TRACE0 Trace Data 7	D	PD_09
TWI0_SCL	TWI0 Serial Clock	Not Muxed	TWI0_SCL
TWI0_SDA	TWI0 Serial Data	Not Muxed	TWI0_SDA
TWI1_SCL	TWI1 Serial Clock	Not Muxed	TWI1_SCL
TWI1_SDA	TWI1 Serial Data	Not Muxed	TWI1_SDA
TWI2_SCL	TWI2 Serial Clock	Not Muxed	TWI2_SCL
TWI2_SDA	TWI2 Serial Data	Not Muxed	TWI2_SDA
UARTO_CTS	UARTO Clear to Send	D	PD_00
UARTO_RTS	UARTO Request to Send	C	PC_15
UARTO_RX	UARTO Receive	C	PC_14
UARTO_TX	UARTO Transmit	C	PC_13
UART1_CTS	UART1 Clear to Send	E	PE_01

Table 19. ADSP-SC58x/ADSP-2158x 529-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
PPI0_D00	EPPI0 Data 0	E	PE_12
PPI0_D01	EPPI0 Data 1	E	PE_11
PPI0_D02	EPPI0 Data 2	E	PE_10
PPI0_D03	EPPI0 Data 3	E	PE_09
PPI0_D04	EPPI0 Data 4	E	PE_08
PPI0_D05	EPPI0 Data 5	E	PE_07
PPI0_D06	EPPI0 Data 6	E	PE_06
PPI0_D07	EPPI0 Data 7	E	PE_05
PPI0_D08	EPPI0 Data 8	E	PE_04
PPI0_D09	EPPI0 Data 9	E	PE_00
PPI0_D10	EPPI0 Data 10	D	PD_15
PPI0_D11	EPPI0 Data 11	D	PD_14
PPI0_D12	EPPI0 Data 12	В	PB_04
PPI0_D13	EPPI0 Data 13	В	PB_05
PPI0_D14	EPPI0 Data 14	В	PB_00
PPI0_D15	EPPI0 Data 15	В	PB_01
PPI0_D16	EPPI0 Data 16	В	PB_02
PPI0_D17	EPPI0 Data 17	В	PB_03
PPI0_D18	EPPI0 Data 18	D	PD_13
PPI0_D19	EPPI0 Data 19	D	PD_12
PPI0_D20	EPPI0 Data 20	E	PE_13
PPI0_D21	EPPI0 Data 21	E	PE_14
PPI0_D22	EPPI0 Data 22	E	PE_15
PPI0_D23	EPPI0 Data 23	D	PD_00
	EPPI0 Data 23 EPPI0 Frame Sync 1 (HSYNC)	E	PE_02
PPIO_FS1 PPIO_FS2	EPPI0 Frame Sync 2 (VSYNC)	E	PE_01
	EPPI0 Frame Sync 3 (FIELD)	C	PC_15
PPIO_FS3	PWM0 Channel A High Side		
PWM0_AH	PWM0 Channel A Low Side	В	PB_07
PWM0_AL		В	PB_08
PWM0_BH	PWM0 Channel B High Side	В	PB_06
PWM0_BL	PWM0 Channel B Low Side	C	PC_00
PWM0_CH	PWM0 Channel C High Side	В	PB_13
PWM0_CL	PWM0 Channel C Low Side	В	PB_14
PWM0_DH	PWM0 Channel D High Side	В	PB_11
PWM0_DL	PWM0 Channel D Low Side	В	PB_12
PWM0_SYNC	PWM0 PWMTMR Grouped	E	PE_09
PWM0_TRIP0	PWM0 Shutdown Input 0	В	PB_15
PWM1_AH	PWM1 Channel A High Side	D	PD_03
PWM1_AL	PWM1 Channel A Low Side	D	PD_04
PWM1_BH	PWM1 Channel B High Side	D	PD_05
PWM1_BL	PWM1 Channel B Low Side	D	PD_06
PWM1_CH	PWM1 Channel C High Side	D	PD_07
PWM1_CL	PWM1 Channel C Low Side	D	PD_08
PWM1_DH	PWM1 Channel D High Side	D	PD_09
PWM1_DL	PWM1 Channel D Low Side	D	PD_10
PWM1_SYNC	PWM1 PWMTMR Grouped	D	PD_11
PWM1_TRIP0	PWM1 Shutdown Input 0	D	PD_02
PWM2_AH	PWM2 Channel A High Side	F	PF_07

Table 19. ADSP-SC58x/ADSP-2158x 529-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
PWM2_AL	PWM2 Channel A Low Side	F	PF_06
PWM2_BH	PWM2 Channel B High Side	F	PF_09
PWM2_BL	PWM2 Channel B Low Side	F	PF_08
PWM2_CH	PWM2 Channel C High Side	D	PD_15
PWM2_CL	PWM2 Channel C Low Side	E	PE_00
PWM2_DH	PWM2 Channel D High Side	E	PE_04
PWM2_DL	PWM2 Channel D Low Side	E	PE_10
PWM2_SYNC	PWM2 PWMTMR Grouped	E	PE_05
PWM2_TRIP0	PWM2 Shutdown Input 0	D	PD_14
GND	Ground	Not Muxed	GND
VDD_EXT	External Voltage Domain	Not Muxed	VDD_EXT
VDD_INT	Internal Voltage Domain	Not Muxed	VDD_INT
RTC0_CLKIN	RTC0 Crystal input / external oscillator connection	Not Muxed	RTC0_CLKIN
RTC0_XTAL	RTC0 Crystal output	Not Muxed	RTC0_XTAL
SINC0_CLK0	SINC0 Clock 0	В	PB_01
SINCO_D0	SINCO Data 0	A	PA_14
SINC0_D1	SINCO Data 1	A	PA_15
SINC0_D2	SINC0 Data 2	В	PB_00
SINC0_D3	SINCO Data 3	В	PB_04
SMC0_A01	SMC0 Address 1	В	PB_05
SMC0_A02	SMC0 Address 2	В	PB_06
SMC0_A03	SMC0 Address 3	В	PB_03
SMC0_A04	SMC0 Address 4	В	PB_02
SMC0_A05	SMC0 Address 5	D	PD_13
SMC0_A06	SMC0 Address 6	D	PD_12
SMC0_A07	SMC0 Address 7	В	PB_01
SMC0_A08	SMC0 Address 8	В	PB_00
SMC0_A09	SMC0 Address 9	A	PA_15
SMC0_A10	SMC0 Address 10	A	PA_14
SMC0_A11	SMC0 Address 11	A	PA_09
SMC0_A12	SMC0 Address 12	A	PA_08
SMC0_A13	SMC0 Address 13	A	PA_13
SMC0_A14	SMC0 Address 14	A	PA_12
SMC0_A15	SMC0 Address 15	A	PA_11
SMC0_A16	SMC0 Address 16	A	PA_07
SMC0_A17	SMC0 Address 17	A	PA_06
SMC0_A17	SMC0 Address 18	A	PA_05
SMC0_A18	SMC0 Address 19	A	PA_04
	SMC0 Address 20		
SMC0_A20 SMC0_A21	SMC0 Address 21	A	PA_01
	SMC0 Address 21	A	PA_00
SMC0_A22	SMC0 Address 23	A	PA_10
SMC0_A23	SMC0 Address 24	A	PA_03
SMC0_A24		A	PA_02
SMC0_A25	SMC0 Address 25	C	PC_12
SMC0_ABE0	SMC0 Byte Enable 1	E	PE_14
SMC0_ABE1	SMC0 Byte Enable 1	E	PE_15
SMC0_AMS0	SMC0 Memory Select 0	C	PC_15
SMC0_AMS1	SMC0 Memory Select 1	E	PE_13

Table 27. ADSP-SC58x/ADSP-2158x Designer Quick Reference (Continued)

Signal Name	Туре	Driver Type	Int Term	Reset Term	Reset Drive	Power Domain	Description and Notes
PC_00	InOut	Н	PullDown	none	none	VDD_EXT	Desc: PORTC Position 0 LP1 Clock PWM0 Channel B Low Side SMC0 Read Enable SPI0 Slave Select Output 4 Notes: No notes
PC_01	InOut	А	PullDown	none	none	VDD_EXT	Desc: PORTC Position 1 SPI2 Clock
PC_02	InOut	А	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 2 SPI2 Master In, Slave Out
PC_03	InOut	А	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 3 SPI2 Master Out, Slave In Notes: No notes
PC_04	InOut	А	PullDown	none	none	VDD_EXT	Desc: PORTC Position 4 SPI2 Data 2
PC_05	InOut	A	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 5 SPI2 Data 3
PC_06	InOut	A	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 6 SPI2 Slave Select Output 1 SPI2 Slave Select Input
PC_07	InOut	A	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 7 CAN0 Receive SMC0 Memory Select 2 SPI0 Slave Select Output 1 TIMER0 Alternate Capture Input
PC_08	InOut	A	PullDown	none	none	VDD_EXT	3 Notes: No notes Desc: PORTC Position 8 CAN0 Transmit SMC0 Memory Select 3
PC_09	InOut	А	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 9 SPI0 Clock
PC_10	InOut	н	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 10 SPI0 Master In, Slave Out
PC_11	InOut	A	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 11 SPI0 Master Out, Slave In TIMER0 Clock
PC_12	InOut	A	PullDown	none	none	VDD_EXT	Notes: No notes Desc: PORTC Position 12 ACM0 External Trigger n SMC0 Address 25 SPI0 Ready SPI0 Slave Select Output 3 Notes: No notes

Total Internal Power Dissipation

Total power dissipation has two components:

- 1. Static, including leakage current
- 2. Dynamic, due to transistor switching characteristics for each clock domain

Many operating conditions can also affect power dissipation, including temperature, voltage, operating frequency, and processor activity. The following equation describes the internal current consumption.

$$\begin{split} I_{DD_INT_TOT} &= I_{DD_INT_STATIC} + I_{DD_INT_CCLK_SHARC1_DYN} + \\ &= I_{DD_INT_CCLK_SHARC2_DYN} + I_{DD_INT_CCLK_A5_DYN} + \\ &= I_{DD_INT_DCLK_DYN} + I_{DD_INT_SYSCLK_DYN} + \\ &= I_{DD_INT_SCLK0_DYN} + I_{DD_INT_SCLK1_DYN} + \\ &= I_{DD_INT_OCLK_DYN} + I_{DD_INT_ACCL_DYN} + \\ &= I_{DD_INT_USB_DYN} + I_{DD_INT_MLB_DYN} + \\ &= I_{DD_INT_GIGE_DYN} + I_{DD_INT_DMA_DR_DYN} + \\ &= I_{DD_INT_GIGE_DYN} + I_{DD_INT_DMA_DR_DYN} + \\ &= I_{DD_INT_PCIE_DYN} \end{split}$$

 $I_{DD_INT_STATIC} \ is the sole contributor to the static power dissipation component and is specified as a function of voltage \\ (V_{DD_INT}) \ and junction temperature (T_{J}) \ in Table 31.$

Table 31. Static Current—I_{DD INT STATIC} (mA)

	Voltage (V _{DD_INT})				
C) رT) (°C)	1.05	1.10	1.15		
-40	7	8	10		
-20	12	14	17		
-10	16	19	23		
0	21	25	30		
10	28	33	39		
25	42	49	58		
40	63	73	84		
55	92	106	122		
70	133	152	175		
85	190	216	247		
100	269	305	346		
105	302	342	387		
115	376	425	480		
125	466	525	592		
133	552	621	700		

The other 14 addends in the $I_{DD_INT_TOT}$ equation comprise the dynamic power dissipation component and fall into four broad categories: application-dependent currents, clock currents, currents from high-speed peripheral operation, and data transmission currents.

Application Dependent Current

The application dependent currents include the dynamic current in the core clock domain of the two SHARC+ cores and the ARM Cortex-A5 core, as well as the dynamic current in the accelerator block.

Dynamic current consumed by the core is subject to an activity scaling factor (ASF) that represents application code running on the processor cores (see Table 32 and Table 33). The ASF is combined with the CCLK frequency and V_{DD_INT} dependent dynamic current data in Table 34 and Table 35, respectively, to calculate this portion of the total dynamic power dissipation component.

 $I_{DD_INT_CCLK_SHARC1_DYN}$ = Table 34 × ASF_{SHARC1} $I_{DD_INT_CCLK_SHARC2_DYN}$ = Table 34 × ASF_{SHARC2} $I_{DD_INT_CCLK_A5_DYN}$ = Table 35 × ASF_{A5}

Table 32. Activity Scaling Factors for the SHARC+ Core1 and Core2 (ASF_{SHARC1} and ASF_{SHARC2})

I _{DD_INT} Power Vector	ASF	
I _{DD-IDLE}	0.31	
I _{DD-NOP}	0.53	
I _{DD-TYP_3070}	0.74	
I _{DD-TYP_5050}	0.87	
I _{DD-TYP_7030}	1.00	
I _{DD-PEAK_100}	1.14	

Table 33. Activity Scaling Factors for the ARM Cortex-A5 Core (ASF_{A5})

I _{DD_INT} Power Vector	ASF
I _{DD-IDLE}	0.29
I _{DD-DHRYSTONE}	0.73
I _{DD-TYP_2575}	0.57
I _{DD-TYP_5050}	0.80
I _{DD-TYP_7525}	1.00
I _{DD-PEAK_100}	1.21

Asynchronous Flash Read

Table 46 and Figure 13 show asynchronous flash memory read timing, related to the SMC.

Table 46. Asynchronous Flash Read

Parameter		Min	Max	Unit
Switching Ch	aracteristics			
t _{AMSADV}	SMC0_Ax (Address)/SMC0_AMSx Assertion Before SMC0_NORDV Low ¹	$PREST \times t_{SCLK0} - 2$		ns
t _{WADV}	SMC0_NORDV Active Low Width ²	$RST \times t_{SCLK0} - 2$		ns
t _{DADVARE}	SMC0_ARE Low Delay From SMC0_NORDV High ³	$PREAT \times t_{SCLK0} - 2$		ns
t _{HARE}	Output ⁴ Hold After SMC0_ARE High ⁵	$RHT \times t_{SCLK0} - 2$		ns
t _{WARE} 6	SMC0_ARE Active Low Width ⁷	$RAT \times t_{SCLK0} - 2$		ns

 $^{^1\}mathrm{PREST}$ value set using the SMC_BxETIM.PREST bits.

 $^{^7\}mathrm{RAT}$ value set using the SMC_BxTIM.RAT bits.

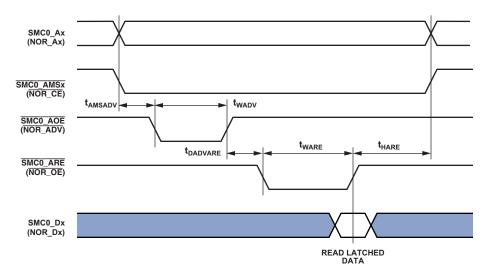


Figure 13. Asynchronous Flash Read

²RST value set using the SMC_BxTIM.RST bits.

³ PREAT value set using the SMC_BxETIM.PREAT bits.

⁴Output signals are SMC0_Ax, SMC0_AMS, SMC0_AOE.

⁵RHT value set using the SMC_BxTIM.RHT bits.

 $^{^{6}}$ SMC0_BxCTL.ARDYEN bit = 0.

Table 66. Serial Ports—Enable and Three-State¹

Parameter		Min	Max	Unit
Switching Ch	paracteristics			
t _{DDTEN}	Data Enable from External Transmit SPTx_CLK ²	1		ns
t _{DDTTE}	Data Disable from External Transmit SPTx_CLK ²		14	ns
t _{DDTIN}	Data Enable from Internal Transmit SPTx_CLK ²	-2.5		ns
t _{DDTTI}	Data Disable from Internal Transmit SPTx_CLK ²		2.8	ns

 $^{^{\}rm 1}{\rm Specifications}$ apply to all eight SPORTs.

²Referenced to drive edge.

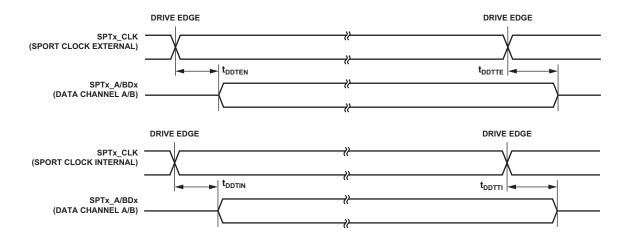


Figure 38. Serial Ports—Enable and Three-State

Sample Rate Converter—Serial Output Port

For the serial output port, the frame sync is an input and it must meet setup and hold times with regard to SCLK on the output port. The serial data output has a hold time and delay specification with regard to serial clock. The serial clock rising edge is the sampling edge, and the falling edge is the drive edge.

Table 70. ASRC, Serial Output Port

Parameter		Min	Max	Unit
Timing Requi	irements			
t _{SRCSFS} 1	Frame Sync Setup Before Serial Clock Rising Edge	4		ns
t _{SRCHFS} 1	Frame Sync Hold After Serial Clock Rising Edge	5.5		ns
t _{SRCCLKW}	Clock Width	t _{SCLK0} – 1		ns
t _{SRCCLK}	Clock Period	2×t _{SCLK0}		ns
Switching Ch	aracteristics			
t _{SRCTDD} 1	Transmit Data Delay After Serial Clock Falling Edge		13	ns
t _{SRCTDH} 1	Transmit Data Hold After Serial Clock Falling Edge	1		ns

¹The serial clock, data, and frame sync signals can come from any of the DAI pins. The serial clock and frame sync signals can also come via PCG or SPORTs. The input of the PCG can be either CLKIN, SCLK0, or any of the DAI pins.

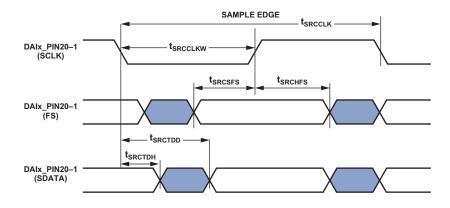


Figure 42. ASRC Serial Output Port Timing

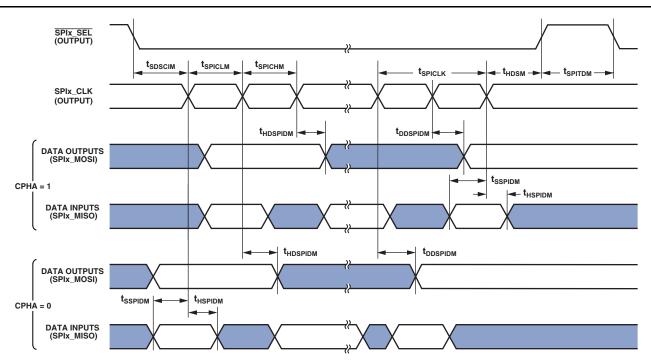


Figure 43. SPI Port—Master Timing

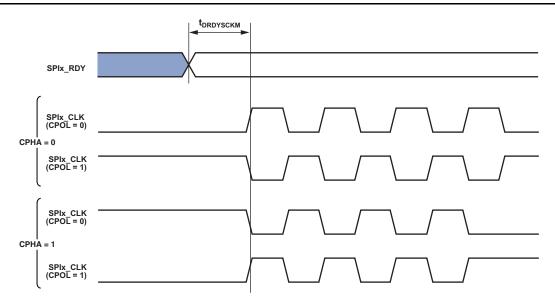


Figure 49. SPIx_CLK Switching Diagram After SPIx_RDY Assertion

PWM — Heightened Precision (HP) Mode Timing

Table 84 and Table 85 and Figure 56 and Figure 57 describe heightened precision (HP) PWM operations.

Table 84. PWM—HP Mode, Output Pulse

Paramete	er	Min	Max	Unit
Switching	Characteristics			
t _{HPWMW}	HP PWM Output Pulse Width ^{1, 2}	$(N + m \times 0.25) \times t_{SCLK} - 0.5$	$(N + m \times 0.25) \times t_{SCLK} + 0.5$	ns

¹N is the DUTY bit field (coarse duty) from the duty register. m is the ENHDIV (Enhanced Precision Divider bits) value from the HP duty register.

² Applies to individual PWM channel with 50% duty cycle. Other PWM channels within the same unit are toggling at the same time. No other GPIO pins toggle.

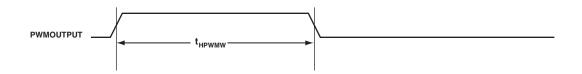


Figure 56. PWM HP Mode Timing, Output Pulse

Table 85. PWM—HP Mode, Output Skew

Parameter	Min	Max	Unit
Switching Characteristics			
t _{HPWMS} HP PWM Output Skew ¹		1.0	ns

Output edge difference between any two PWM channels (AH, AL, BH, BL, CH, CL, DH and DL) in the same PWM unit (a unit is PWMx where x = 0, 1, 2), with the same HP edge placement.

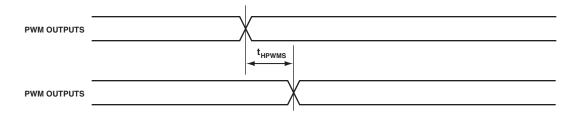


Figure 57. PWM HP Mode Timing, Output Skew

Mobile Storage Interface (MSI) Controller Timing

Table 101 and Figure 74 show I/O timing related to the MSI.

Table 101. MSI Controller Timing

Param	eter	Min	Max	Unit
Timing	Requirements			
t _{ISU}	Input Setup Time	4.8		ns
t _{IH}	Input Hold Time	-0.5		ns
Switchi	ng Characteristics			
f_{PP}	Clock Frequency Data Transfer Mode ¹		50	MHz
t_{WL}	Clock Low Time	8		ns
t_{WH}	Clock High Time	8		ns
t _{TLH}	Clock Rise Time		3	ns
t _{THL}	Clock Fall Time		3	ns
t _{ODLY}	Output Delay Time During Data Transfer Mode		2	ns
t _{OH}	Output Hold Time	-1.8		ns

 $^{^{1}}t_{PP} = 1/f_{PP}$.

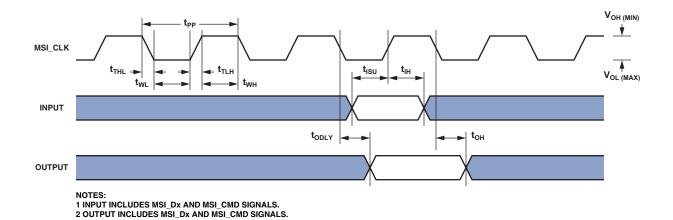


Figure 74. MSI Controller Timing

ADSP-SC58x/ADSP-2158x 529-BALL BGA BALL ASSIGNMENTS

The ADSP-SC58x/ADSP-2158x 529-Ball BGA Ball Assignments (Numerical by Ball Number) table lists the 529-ball BGA package by ball number.

The ADSP-SC58x/ADSP-2158x 529-Ball BGA Ball Assignments (Alphabetical by Pin Name) table lists the 529-ball BGA package by pin name.

ADSP-SC58x/ADSP-2158x 529-BALL BGA BALL ASSIGNMENTS (NUMERICAL BY BALL NUMBER)

Ball No.	Pin Name	Ball No.	Pin Name	Ball No.	Pin Name	Ball No.	Pin Name
A01	GND	B19	DMC1_DQ11	D14	DMC1_BA2	F09	GND
A02	DMC0_UDQS	B20	DMC1_DQ12	D15	DMC1_CAS	F10	VDD_INT
A03	DMC0_CK	B21	DMC1_DQ14	D16	DMC1_RAS	F11	VDD_INT
A04	DMC0_CK	B22	PD_00	D17	DMC1_A09	F12	VDD_INT
A05	DMC0_DQ09	B23	PD_04	D18	DMC1_A15	F13	VDD_INT
A06	DMC0_LDQS	C01	DMC0_DQ14	D19	DMC1_A10	F14	VDD_INT
A07	DMC0_LDQS	C02	DMC0_DQ13	D20	DMC1_A11	F15	VDD_INT
A08	DMC0_DQ05	C03	DMC0_CS0	D21	PC_14	F16	GND
A09	DMC0_DQ03	C04	DMC0_CKE	D22	PD_10	F17	VDD_INT
A10	DMC0_DQ01	C05	DMC0_LDM	D23	PD_09	F18	VDD_INT
A11	DMC1_DQ03	C06	DMC1_RESET	E01	DMC0_A04	F19	VDD_INT
A12	DMC1_DQ00	C07	DMC1_A03	E02	DMC0_RAS	F20	PE_06
A13	DMC1_LDQS	C08	DMC1_A00	E03	DMC0_BA1	F21	PD_02
A14	DMC1_LDQS	C09	DMC1_A01	E04	DMC0_WE	F22	PD_13
A15	DMC1_VREF	C10	DMC1_A04	E05	DMC0_RZQ	F23	PD_12
A16	DMC1_CK	C11	DMC1_A06	E06	GND	G01	DMC0_A13
A17	DMC1_CK	C12	DMC1_BA1	E07	GND	G02	DMC0_A09
A18	DMC1_DQ09	C13	DMC1_ODT	E08	GND	G03	DMC0_A03
A19	DMC1_UDQS	C14	DMC1_CS0	E09	GND	G04	DMC0_A11
A20	DMC1_UDQS	C15	DMC1_LDM	E10	VDD_INT	G05	VDD_INT
A21	DMC1_DQ13	C16	DMC1_UDM	E11	VDD_INT	G06	VDD_DMC
A22	DMC1_DQ15	C17	DMC1_A14	E12	VDD_INT	G07	VDD_DMC
A23	GND	C18	DMC1_A12	E13	VDD_INT	G08	VDD_DMC
B01	DMC0_UDQS	C19	DMC1_A13	E14	VDD_INT	G09	VDD_DMC
B02	DMC0_DQ12	C20	PC_13	E15	VDD_INT	G10	VDD_DMC
B03	DMC0_DQ11	C21	PD_01	E16	VDD_INT	G11	VDD_DMC
B04	DMC0_DQ10	C22	PD_06	E17	VDD_INT	G12	VDD_DMC
B05	DMC0_DQ08	C23	PD_05	E18	VDD_INT	G13	VDD_DMC
B06	DMC0_DQ06	D01	DMC0_VREF	E19	DMC1_RZQ	G14	VDD_DMC
B07	DMC0_DQ07	D02	DMC0_DQ15	E20	PC_15	G15	VDD_DMC
B08	DMC0_DQ04	D03	DMC0_BA0	E21	PD_08	G16	VDD_DMC
B09	DMC0_DQ02	D04	DMC0_BA2	E22	PD_14	G17	VDD_DMC
B10	DMC0_DQ00	D05	DMC0_ODT	E23	PD_11	G18	VDD_DMC
B11	DMC1_DQ01	D06	DMC0_UDM	F01	DMC0_A01	G19	VDD_INT
B12	DMC1_DQ02	D07	DMC1_A05	F02	DMC0_A06	G20	PE_04
B13	DMC1_DQ04	D08	DMC1_WE	F03	DMC0_CAS	G21	PE_13
B14	DMC1_DQ05	D09	DMC1_A07	F04	DMC0_A02	G22	PE_01
B15	DMC1_DQ06	D10	DMC1_A02	F05	DMC0_A07	G23	PE_00
B16	DMC1_DQ07	D11	DMC1_BA0	F06	GND	H01	DMC0_A14
B17	DMC1_DQ08	D12	DMC1_A08	F07	VDD_INT	H02	DMC0_A12
B18	DMC1_DQ10	D13	DMC1_CKE	F08	VDD_INT	H03	DMC0_A05